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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Akira OTANI et al.

Confirmation No. : 8957

Group Art Unit : 1773

Serial No : 10/595,914  
(National Stage of PCT/JP2004/017944)

Examiner : Not Yet Assigned

I.A. Filed : December 2, 2004

For : ANISOTROPIC CONDUCTIVE ADHESIVE SHEET AND  
CONNECTING STRUCTURE

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
U.S. Patent and Trademark Office  
Customer Service Window, Mail Stop: Amendment  
Randolph Building  
401 Dulany Street  
Alexandria VA 22314

Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, Applicant hereby brings to the attention of the Examiner the following documents cited in the International Search Report of International Patent Application No. PCT/JP2004/017944, of which the present application is the U.S. National Stage:

- (1) JP 11-121072 A, April 30, 1999, accompanied by an English language abstract thereof (provided by esp@cenet);
- (2) JP 2002-519473 A, July 2, 2002; Applicants note that this document is cited and discussed at page 2, line 16; at page 3, line 10; and at page 4, line 26 of the present application;
- (3) U.S. Patent Application Publication No. 2001/0008169 A1 (CONNELL et al.), July 19, 2001; Applicants note that this document is a family member of document (2);

- (4) JP 2000-149677 A, May 30, 2000, accompanied by an English language abstract thereof (provided by esp@cenet);
- (5) JP 2002-358825 A, December 13, 2002, accompanied by an English language abstract thereof (provided by esp@cenet);
- (6) JP 2003-64324 A, March 5, 2003, accompanied by an English language abstract thereof (provided by esp@cenet);
- (7) JP 2-117980 A, May 2, 1990; Applicants note that this document is cited and discussed at page 2, line 23; at page 3, line 28; and at page 4, line 27 of the present application;
- (8) U.S. Patent No. 5,240,761 (CALHOUN et al.), August 31, 1993; Applicants note that this document is a family member of document (7).

Applicants further direct the Examiner's attention to the following documents cited and discussed in the present application:

- (9) JP 6-349339 A, December 22, 1994, accompanied by an English language abstract thereof (provided by esp@cenet); Applicants note that this document is cited and discussed at page 1, line 18 and at page 4, line 21 of the present application;
- (10) JP 2895872 B2, March 5, 1999, accompanied by an English language abstract thereof (provided by esp@cenet); Applicants note that this document is cited and discussed at page 1, line 21 and at page 4, line 22 of the present application;
- (11) JP 3165477 B2, March 2, 2001, accompanied by an English language abstract thereof (provided by esp@cenet); Applicants note that this document

is cited and discussed at page 2, line 10 and at page 4, line 25 of the present application;

- (12) JP 6-60712 A, March 4, 1994, accompanied by an English language abstract thereof (provided by Patent Abstracts of Japan); Applicants note that this document is cited and discussed at page 2, line 1 and at page 4, line 23 of the present application;
- (13) JP 6-45024 A, February 18, 1994, accompanied by an English language abstract thereof (provided by esp@cenet); Applicants note that this document is cited and discussed at page 2, line 4 and at page 4, line 24 of the present application.

Furthermore, Applicants direct the Examiner's attention to the following co-pending and commonly assigned U.S. applications:

- (14) U.S. Application Serial No. 10/567,022 filed February 3, 2006 and entitled "COMPOSITE POROUS MEMBRANE AND PROCESS FOR PRODUCING THE SAME";
- (15) U.S. Application Serial No. 10/574,837 filed April 6, 2006 and entitled "POLYOXYMETHYLENE RESIN COMPOSITION AND MOLDINGS THEREOF";
- (16) U.S. Application Serial No. 10/576,259 filed April 18, 2006 and entitled "POLYTRIMETHYLENE TEREPHTHALATE REINFORCED RESIN COMPOSITION";
- (17) U.S. Application Serial No. 10/582,556 filed June 9, 2006 and entitled "THERMOPLASTIC RESIN COMPOSITION";

- (18) U.S. Application Serial No. 10/597,091 filed July 11, 2006 and entitled "RESIN AND RESIN COMPOSITION";
- (19) U.S. Application Serial No. 10/597,336 filed July 20, 2006 and entitled "POLYACETAL RESIN COMPOSITION".

Copies of the above-listed documents (with the exception of U.S. patents and U.S. patent applications) and the International Search Report (in English) for International Application PCT/JP2004/017944 are enclosed together with a completed copy of the PTO-1449 Form listing these documents. Accordingly, the Examiner is requested to consider these documents and to indicate such consideration by returning a signed and initialed copy of the PTO-1449 Form with the next official communication.

Further to 37 C.F.R. §1.98 (a)(2)(ii), copies of the U.S. patent and patent application publication are not enclosed herewith. However, if any copy is needed, the Examiner is respectfully requested to contact the undersigned.

Inasmuch as this Information Disclosure Statement is filed within three months of entering the national stage, no fee is needed to ensure consideration of the submitted material. However, if a fee is deemed necessary, the Patent and Trademark Office is hereby authorized to charge Deposit Account No. 19-0089 any fee necessary to ensure consideration of the submitted materials.

If there are any questions with regard to this submission, the Examiner is requested to contact the undersigned at the telephone number listed below.

Respectfully submitted,  
Akira OTANI et al.



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FORM PTO-1449

Department of Commerce  
Patent and Trademark OfficeAtty. Docket No.  
P29987Application No.  
10/595,914INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT  
(Use several sheets if necessary)Applicant  
Akira OTANI et al.Filing Date  
I.A. Filed December 2, 2004Group  
1773

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	2001 /	0 0 0 8 1 6 9	07/19/01	CONNELL et al.			
		5 2 4 0 7 6 1	08/31/93	CALHOUN et al.			

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	1 1	- 1 2 1 0 7 2	04/30/99	JAPAN			
	2 0 0 2	- 5 1 9 4 7 3	07/02/02	JAPAN			
	2 0 0 0	- 1 4 9 6 7 7	05/30/00	JAPAN			
	2 0 0 2	- 3 5 8 8 2 5	12/13/02	JAPAN			
	2 0 0 3	- 0 6 4 3 2 4	03/05/03	JAPAN			
	2	- 1 1 7 9 8 0	05/02/90	JAPAN			
	6	- 3 4 9 3 3 9	12/22/94	JAPAN			
		2 8 9 5 8 7 2	03/05/99	JAPAN			
		3 1 6 5 4 7 7	03/02/01	JAPAN			
	6	- 0 6 0 7 1 2	03/04/94	JAPAN			
	6	- 0 4 5 0 2 4	02/18/94	JAPAN			

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	1	English Language Abstract of JP 11-121072.
	2	English Language Abstract of JP 2000-149677.
	3	English Language Abstract of JP 2002-358825.
	4	English Language Abstract of JP 2003-064324.
	5	English Language Abstract of JP 6-349339.
	6	English Language Abstract of JP 2895872.
	7	English Language Abstract of JP 3165477.
	8	English Language Abstract of JP 6-060712.
	9	English Language Abstract of JP 6-045024.
	10	U.S. Application Serial No. 10/567,022 filed February 3, 2006 and entitled "COMPOSITE POROUS MEMBRANE AND PROCESS FOR PRODUCING THE SAME".
	11	U.S. Application Serial No. 10/574,837 filed April 6, 2006 and entitled "POLYOXYMETHYLENE RESIN COMPOSITION AND MOLDINGS THEREOF".
	12	U.S. Application Serial No. 10/576,259 filed April 18, 2006 and entitled "POLYTRIMETHYLENE TEREPHTHALATE REINFORCED RESIN COMPOSITION".
	13	U.S. Application Serial No. 10/582,556 filed June 9, 2006 and entitled "THERMOPLASTIC RESIN COMPOSITION".
	14	U.S. Application Serial No. 10/597,091 filed July 11, 2006 and entitled "RESIN AND RESIN COMPOSITION".
	15	U.S. Application Serial No. 10/597,336 filed July 20, 2006 and entitled "POLYACETAL RESIN COMPOSITION".

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.